

REMARKS

This responds to the Office Action mailed on August 14, 2006.

Claims 1, 2, 4, 6, 7, 12, 13, 15, and 18 are amended, and no claims are cancelled or added; as a result, claims 1-4, 6-9, 11-15, 17, and 18 remain pending in this application.

§112 Rejection of the Claims

Claim 2 was rejected under 35 U.S.C. § 112, second paragraph, for indefiniteness. Claim 12 was believed to be clear and definite as it previously stood, but has been rewritten in an attempt to make it more easily understood.

Claim Objections

Claims 4, 6, 12, 15 and 18 were objected to for consistency of claim terminology or clarity of description. Claims 4, 6, 12, 15 and 18 have been amended. Withdrawal of the rejection is respectfully rejected.

§102 Rejection of the Claims

Claims 1, 2 and 13 were rejected under 35 U.S.C. § 102(b) for anticipation by Bruns, Maschotta and Anderson.

Claims 6 and 15 were rejected under 35 U.S.C. § 102(b) for anticipation by either Maschotta or Anderson.

Claim 14 was rejected under 35 U.S.C. § 102(b) for anticipation by Maschotta.

§103 Rejection of the Claims

Claims 3, 4, 7-9 and 11 were rejected under 35 U.S.C. § 103(a) as being unpatentable over any of Bruns, Maschotta and Anderson in view of Forbes et al. (all of record).

Claim 12 was rejected under 35 U.S.C. § 103(a) as being unpatentable over any of Maschotta or Anderson in view of Forbes et al.

Claims 17 and 18 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Bruns, Maschotta or Anderson in view of Adachi (all of record).

Each of these rejected claims contained a limitation such that the dielectric coating comprises a coating material applied over the at least one microstrip line in a thickness greater than an average thickness of the coating material across the printed circuit board. In other words, the conformal coating applied to the circuit board has an average coating thickness, and the thickness of the conformal coating over the microstrip lines is greater than this average thickness.

This is contrary to what is shown in the references, such as in Bruns where the overlay layer 6 is actually thinner over the striplines than it is over other areas of the base dielectric layer. The coating over the striplines in Burns is therefore not greater than the average conformal coating thickness, but is smaller than the average conformal coating thickness. Similarly, Maschotta and Anderson also show that the coating over a microstrip line area is less than the overlay coating in other places.

As the average value language seems to be difficult to understand, the independent claims have been rewritten to more clearly reflect that the conformal thickness coating over the at least one microstrip line is greater in thickness than the conformal coating thickness over at least some other portion of the printed circuit board having the conformal coating. More specifically, the dielectric coating comprises a coating material applied over the first microstrip line in a thickness greater than a thickness of the coating material in at least one other area of the substrate having the coating material applied thereto.

This language distinguishes the pending claims from each of the three references, and is believed to be more easily understood than the previous claim language. Reexamination and allowance of the pending independent claims 1, 7, 13, and 18, and of the claims that depend therefrom, is therefore respectfully requested.

CONCLUSION

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney (612) 349-9581 to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

ROY GREEFF

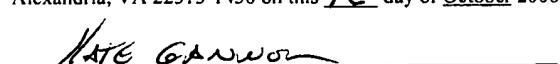
By his Representatives,

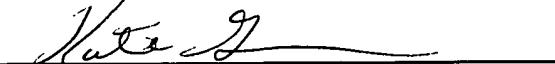
SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
P.O. Box 2938
Minneapolis, MN 55402
(612) 349-9581

Date Oct 16 06

By 
John M. Dahl
Reg. No. 44,639

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